

AMENDMENTS TO THE SPECIFICATION:

Please change the title throughout, declaration accepted, as follows:

--A SEMICONDUCTOR PACKAGE HAVING ENCAPSULATED CHIP
ATTACHED TO A MOUNTING PLATE, AND PRODUCTION PROCESS FOR
MANUFACTURING SUCH SEMICONDUCTOR PACKAGE--.

Please replace the paragraph beginning at page 23, line 11, with the following rewritten paragraph:

--With reference to [[Figs.]] Fig. 33, a third embodiment of the semiconductor package according to the present invention is schematically illustrated in a partial perspective view. In the third embodiment, the semiconductor package is constructed as a low power diode package. Similar to the above-mentioned embodiments, a first lead frame and a second lead frame are used to manufacture the low power diode package.--